



US00D410916S

United States Patent [19] Oba

[11] **Patent Number: Des. 410,916**

[45] **Date of Patent: ** Jun. 15, 1999**

[54] **CASE FOR SEMICONDUCTOR ELEMENT**

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[73] Assignee: **Sony Corporation**, Tokyo, Japan

[**] Term: **14 Years**

[21] Appl. No.: **29/073,021**

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[51] **LOC (6) Cl.** **14-99**

[52] **U.S. Cl.** **D14/120**

[58] **Field of Search** D13/182, 184;
D14/120, 121; 296/308.1, 308.3; 369/75.1,
77.2, 272, 275.1, 275.2, 275.3, 280, 292

[56] **References Cited**

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[57] **CLAIM**

The ornamental design for a case for a semiconductor element, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a case for a semiconductor element showing my new design;

FIG. 2 is a top plan view thereof;

FIG. 3 is a left side elevational view thereof;

FIG. 4 is a front elevational view thereof;

FIG. 5 is a bottom plan view thereof;

FIG. 6 is a right side elevational view thereof; and,

FIG. 7 is a rear elevational view thereof.

1 Claim, 3 Drawing Sheets

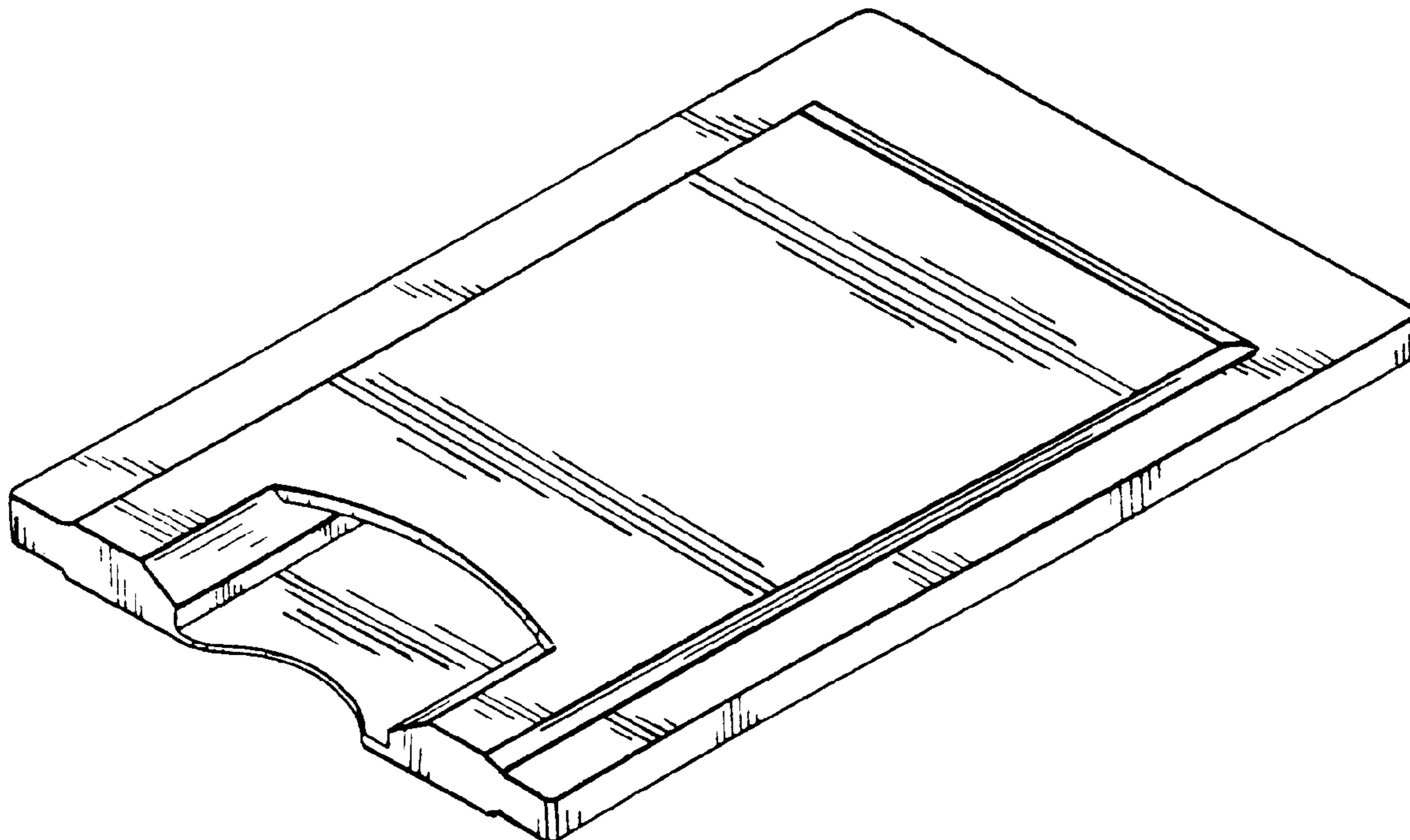


FIG. 1

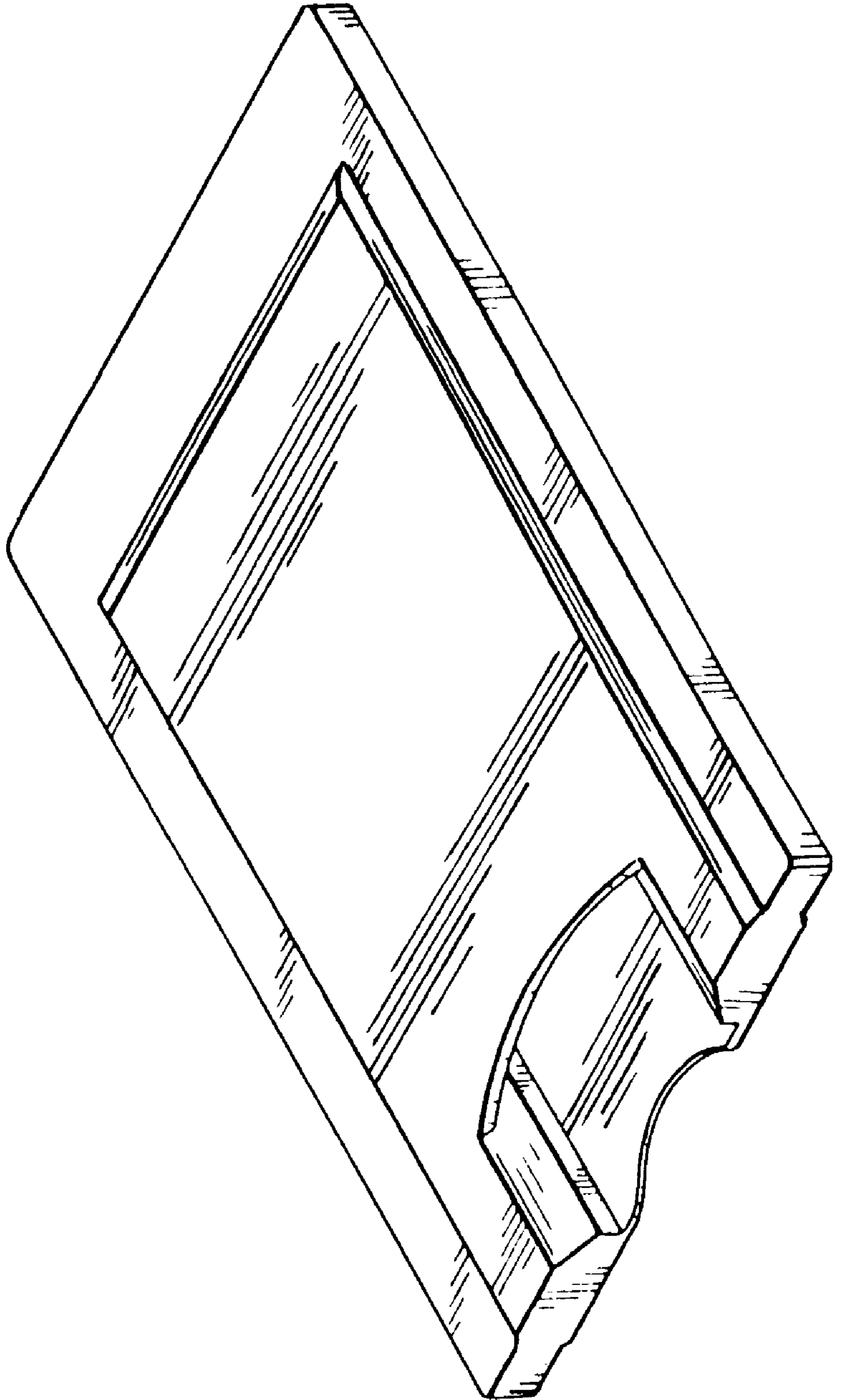


FIG. 2



FIG. 4

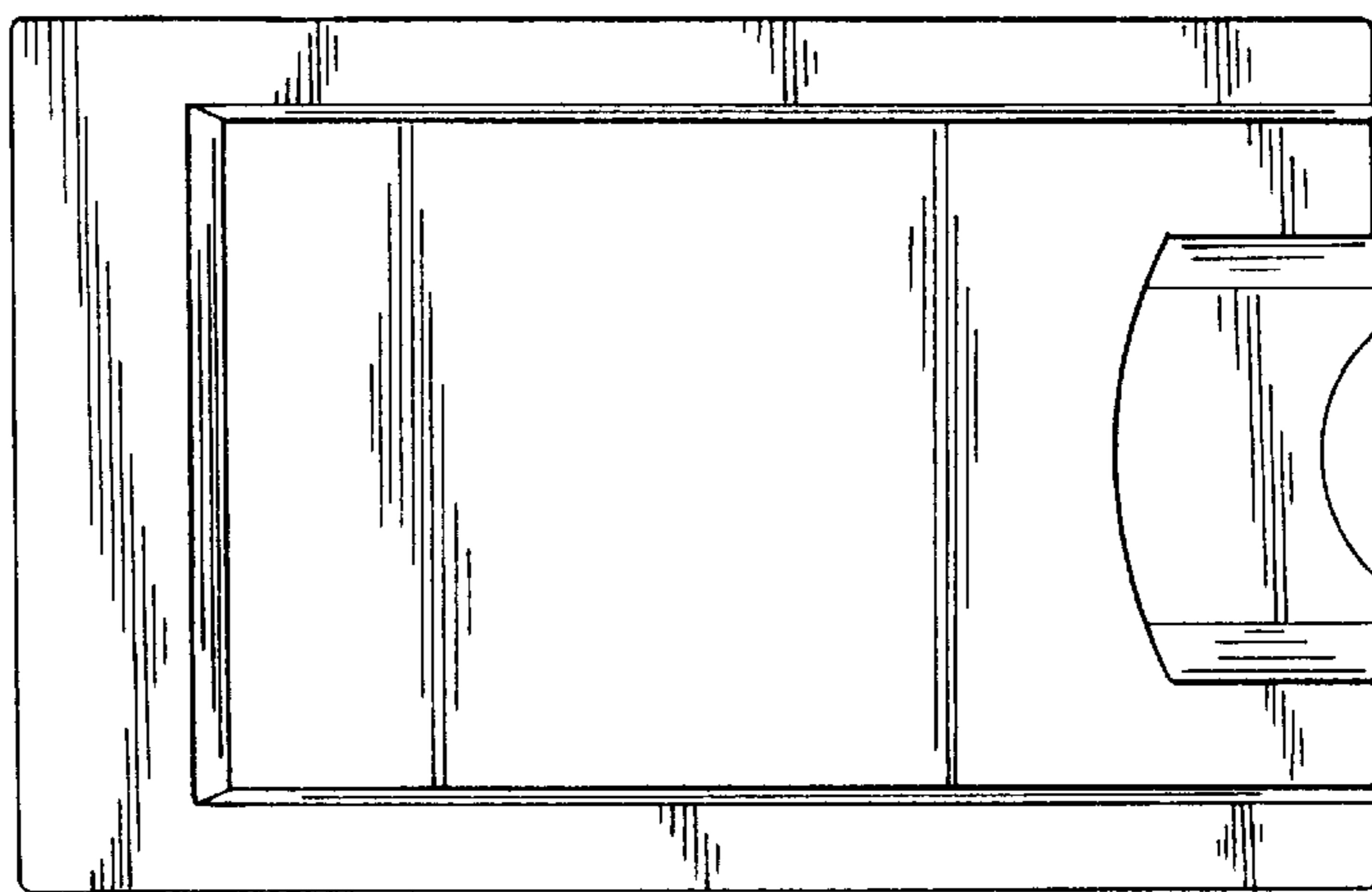


FIG. 5



FIG. 6

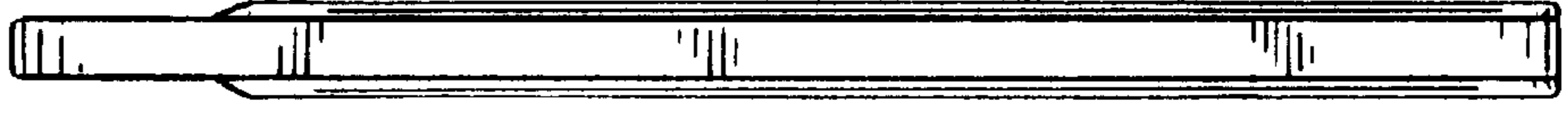


FIG. 7

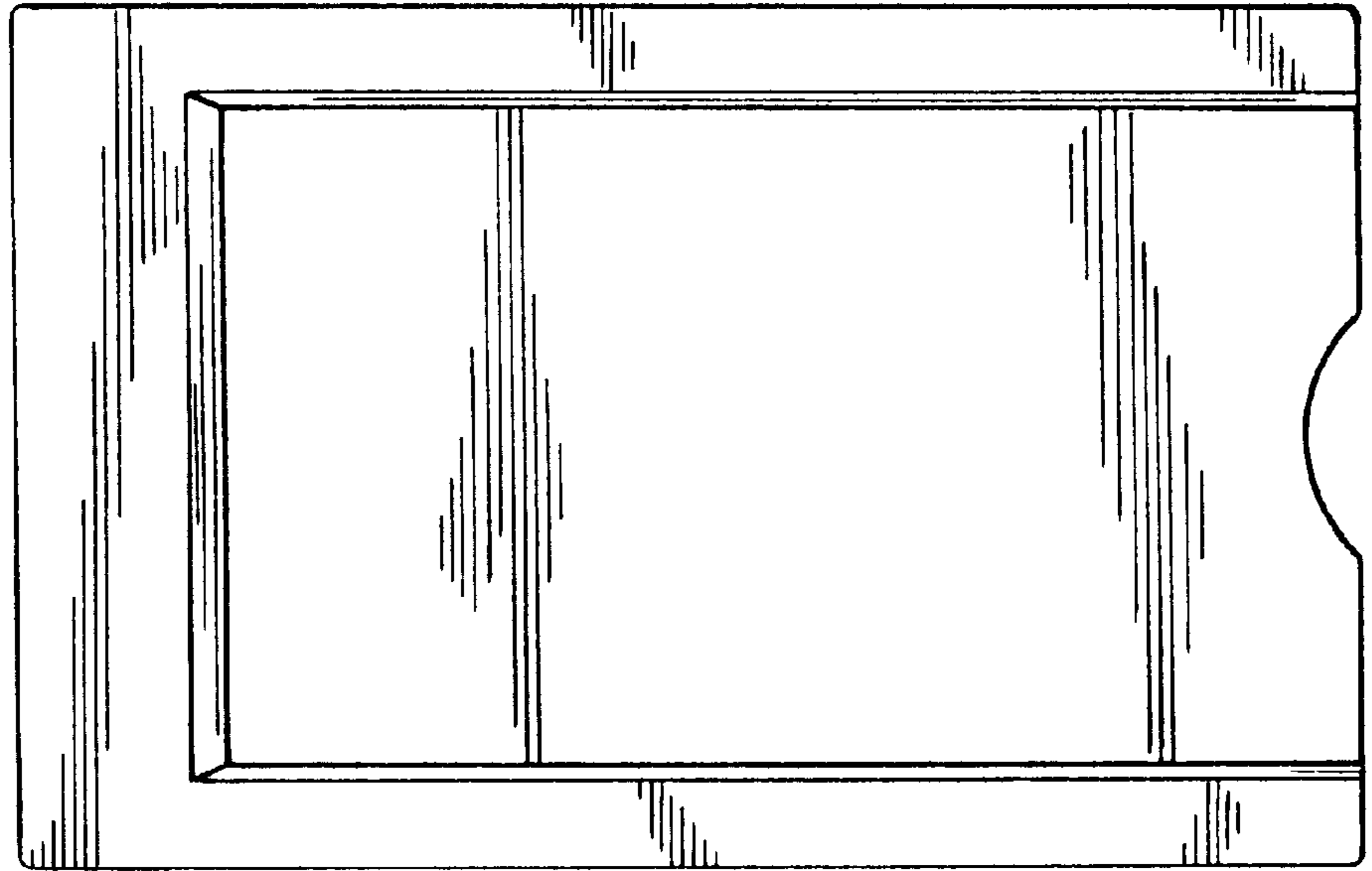


FIG. 3

